

**Polymer
PTC Devices**

Surface mount fuses

Shanghai Wayon Thermo/Electro Materials Co.,Ltd.
4th Floor, No.201, New Jinqiao Road, Shanghai 201206,China
Tel: 86-21- 50320161 58995165 Fax: 86-21-50320266
E-mail: market@way-on.com [Http://www.way-on.com](http://www.way-on.com)



LP-USM005

Features

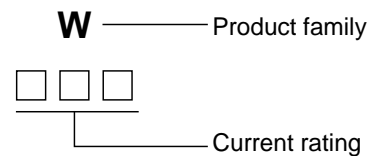
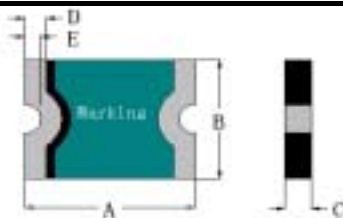
- Smaller size of 1210
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-USM005	3.43	2.80	1.25	0.60	0.20

Part Marking System

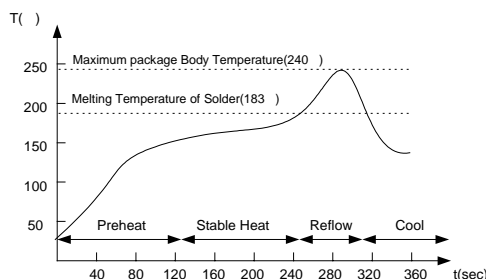
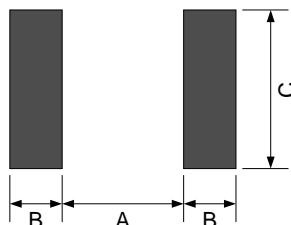


Electrical Characteristics

Part number	I _H	I _T	V _{max}	I _{max}	T _{trip}	Pd _{typ}	R _{min}	R _{1max}
	(A)	(A)	(V)	(A)	Current(A) Time(S)	(W)	()	()
LP-USM005	0.05	0.15	30	10	1.5 0.25	1.0	3.60	50.0

I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.
 I_T=Trip current: minimum current at which the device will always trip at 25 °C still air.
 V_{max}=Maximum voltage device can withstand without damage at rated current.
 I_{max}=Maximum fault current device can withstand without damage at rated voltage.
 T_{trip}=Maximum time to trip(s) at assigned current.
 Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min}=Minimum device resistance at 25 °C prior to tripping.
 R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-USM005	2.00	1.00	2.50

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.